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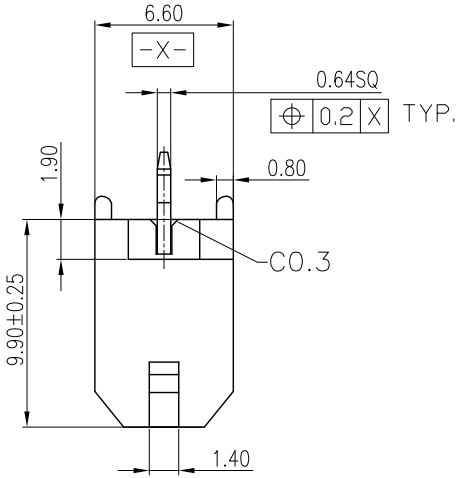
The marking on thisproduct doesn't contain environmental hazardous materials per Material Specification SS-00259 for Sony GP compliant or per directive 2011/65/EC for RoHS compliant.

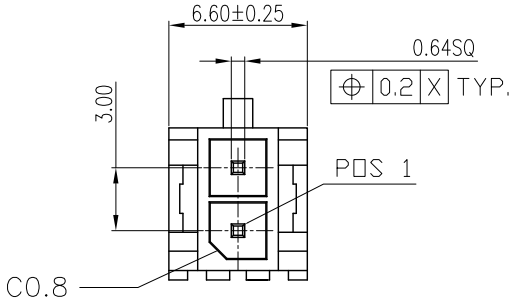
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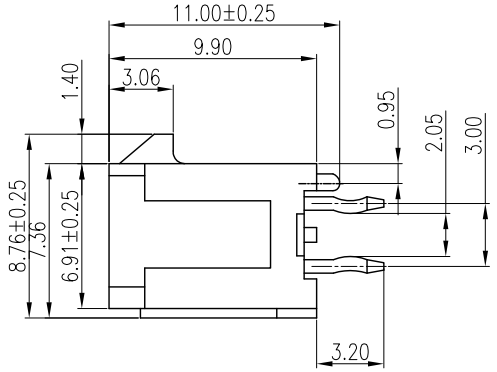
REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A	NE-12120	RELEASE FOR RoHS	07/09/2012	Arron Lin
B	NE-13034	MODIFY PLATING TO OVERALL	03/13/2013	Arron Lin



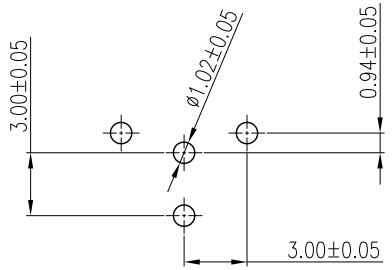


PART NO. G881A021X2T2EU

CONTACT FINISH
0: Tin
1: FLASH GOLD
2: 15 u" GOLD
3: 30 u" GOLD



NOTE:
1.INSULATOR: HIGH TEMP. THERMOPLASTIC, LCP, UL 94V-0,
COLOR: BLACK.
2.CONTACT MATERIAL:COPPER ALLOY;
3.FINISH:
CONTACT SELECTIVE PLATING OPTIONS OVREALL.
UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN. OVERALL.
4.THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EC FOR RoHS.
5.APPLICABLE P.C.BOARD THICKNESS: 1.60mm
6.PACKING MUST BE PER Amphenol PACKING SPECIFICATION



2X1POSITIONS

RECOMMENDED PCB LAYOUT

TOLERANCE	APPROVALS	DATE	TITLE
X.	DRAWN Debby Hung	03/13/2013	G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT PCB MOUNT (2*1 POS)
X.X ±0.30 X.XX ±0.20 X.XXX ±0.10	CHECKED Roger Tsai	03/13/2013	
ANGULAR ±1°	APPROVED Arron Lin	03/13/2013	
UNLESS OTHERWISE SPECIFIED	DWG TYPE CUST DWG	PROJECT CODE PHD	

UNIT	SIZE	PART No.
mm	A3	G881A021X2T2EU
SCALE	SHEET	DWG No. / REV.
NA	1 OF 2	G881A021X2T2EU / B

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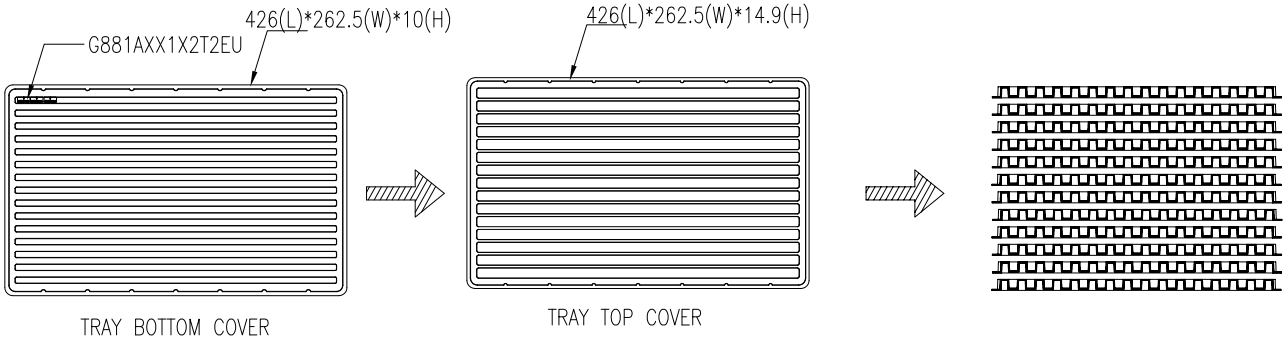
The marking on thisproduct doesn't contain environmental hazardous materials per Material Specification SS-00259 for Sony GP compliant or per directive 2011/65/EC for RoHS compliant.

Amphenol Taiwan RoHS Compliant 2011/65/EU

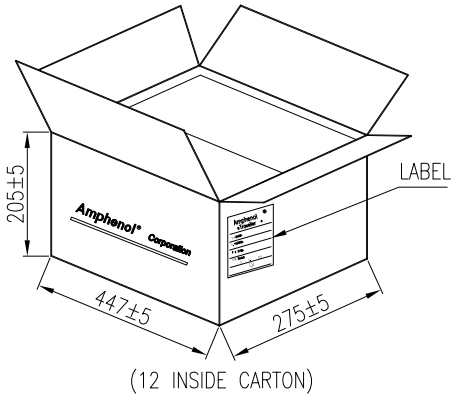
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REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A	NE-12120	RELEASE FOR RoHS	07/09/2012	Arron Lin
B	NE-13034	MODIFY PLATING TO OVERALL	03/13/2013	Arron Lin



POS	PCS/TRAY	PCS/CARTON
02	900	10,800



NOTE:
1. MATERIAL : BLACK CONDUCTIVE POLYSTYRENE ALLOY
2. ALL DIMENSIONS MEET EIA-481-C REQUIREMENTS.
3. THICKNESS : 0.80±0.05mm.

TOLERANCE	APPROVALS	DATE	TITLE
X. ±0.30 X.X ±0.20 X.XX ±0.10 X.XXX ±0.10 ANGULAR ±1° UNLESS OTHERWISE SPECIFIED	DRAWN Debby Hung	03/13/2013	G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT PCB MOUNT (2*1 POS)
	CHECKED Roger Tsai	03/13/2013	
	APPROVED Arron Lin	03/13/2013	
	DWG TYPE CUST DWG	PROJECT CODE PHD	

UNIT	SIZE	PART No.
mm	A3	G881AXX1X2T2EU
SCALE	SHEET	DWG No. / REV.
NA	2 OF 2	G881AXX1X2T2EU / B

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